



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



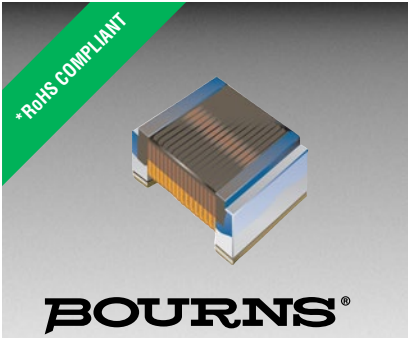
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Features

- 0805 size
- Available in E12 series
- High Q up to 80 typ.
- High operating temperature of 125 °C
- Small size of only 2.0 mm
- RoHS compliant*

Applications

- Mobile phones
- Cellular phones
- CTV, VCR, HIC, FDD

BOURNS®

CW201212 Series - High Q Chip Inductors

Electrical Specifications

Bourns® Part No.	Inductance		Q	Test Freq. (MHz)		SRF (MHz)	RDC (Ohms)		I rms (mA)
	nH	Tol. %		Min.	L		Q	Min.	
CW201212-2N2J	2.2	±5	50	250	1000	6000	0.06	600	
CW201212-2N7J	2.7	±5	35	250	1000	6000	0.08	600	
CW201212-2N8J	2.8	±5	32	250	1000	6000	0.06	800	
CW201212-3N3J	3.3	±5	30	250	1500	6000	0.08	600	
CW201212-3N9J	3.9	±5	60	250	1000	6000	0.06	600	
CW201212-4N7J	4.7	±5	60	250	1000	5800	0.06	600	
CW201212-5N6J	5.6	±5	60	250	1000	5800	0.08	600	
CW201212-6N8J	6.8	±5	60	250	1000	5800	0.06	600	
CW201212-8N2J	8.2	±5	60	250	1000	5500	0.06	600	
CW201212-10NJ	10	±5	60	250	500	4800	0.08	600	
CW201212-12NJ	12	±5	60	250	500	4100	0.08	600	
CW201212-15NJ	15	±5	60	250	500	3600	0.08	600	
CW201212-18NJ	18	±5	60	250	500	3400	0.08	600	
CW201212-22NJ	22	±5	60	250	500	3300	0.10	600	
CW201212-27NJ	27	±5	60	250	500	2600	0.12	600	
CW201212-33NJ	33	±5	60	250	500	2400	0.15	500	
CW201212-39NJ	39	±5	60	250	500	2100	0.18	500	
CW201212-47NJ	47	±5	60	200	500	1700	0.15	500	
CW201212-56NJ	56	±5	60	200	500	1600	0.25	500	
CW201212-68NJ	68	±5	60	200	500	1450	0.27	500	
CW201212-82NJ	82	±5	60	150	500	1350	0.32	500	
CW201212-R10J	100	±5	60	150	500	1200	0.43	400	
CW201212-R12J	120	±5	50	150	250	1100	0.48	400	
CW201212-R15J	150	±5	50	100	250	950	0.67	400	
CW201212-R18J	180	±5	50	100	250	900	0.85	350	
CW201212-R22J	220	±5	50	100	250	860	1.10	300	
CW201212-R27J	270	±5	45	100	250	850	1.46	250	
CW201212-R33J	330	±5	45	100	250	800	1.65	200	
CW201212-R39J	390	±5	45	100	250	780	2.20	170	
CW201212-R47J	470	±5	33	250	100	375	1.72	250	
CW201212-R56J	560	±5	23	50	50	340	1.90	230	
CW201212-R68J	680	±5	23	25	50	270	2.05	190	
CW201212-R82J	820	±5	23	25	50	230	2.30	180	
CW201212-R91J	910	±5	22	22	50	220	2.50	150	

Note: 2 % tolerance available for inductance ranges of 12 nH and above.
Replace "J" with "G".

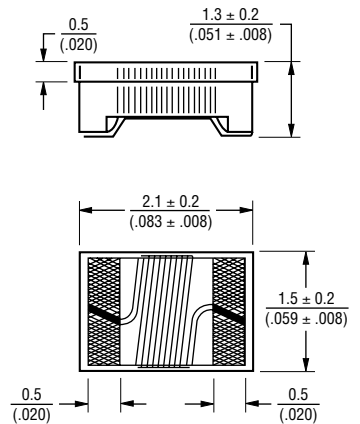
General Specifications

Temperature Rise40 °C max. at rated current
 Operating Temperature-40 °C to +125 °C
 Storage Temperature-40 °C to +125 °C
 Reflow Soldering .. 230 °C, 50 sec. max.
 Resistance to Soldering Heat +260 °C, 5 seconds

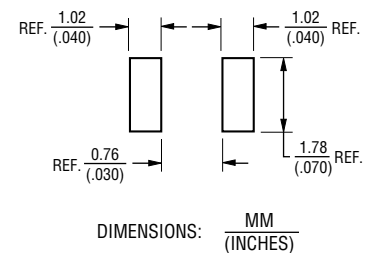
Materials

Core Material
 -2N2J through -R39J.....Ceramic
 -R47J through -R91J.....Ferrite
 Wire Enameled copper (1W1E180)
 Terminal Mo/Mn+Ni+Au
 Packaging..... 2,000 pcs. per reel

Product Dimensions



Recommended Layout



*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

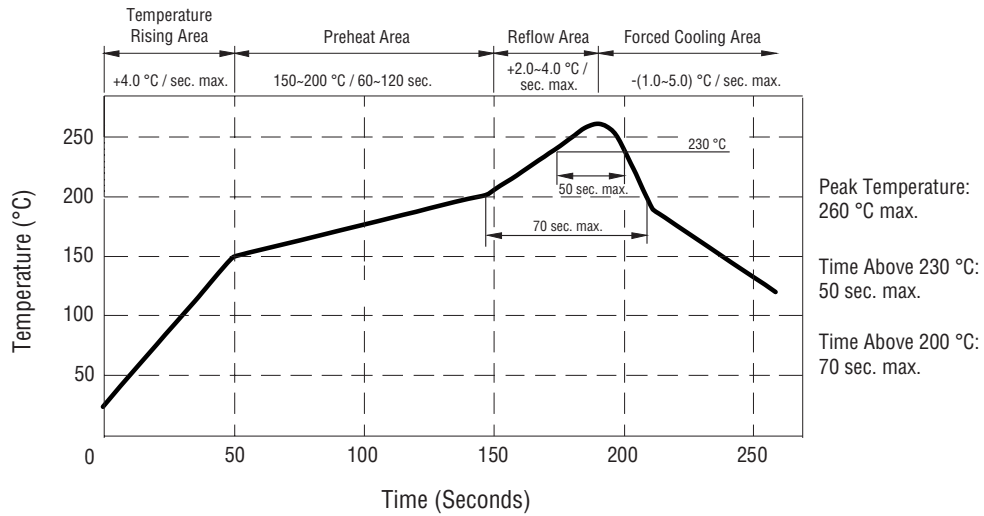
Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

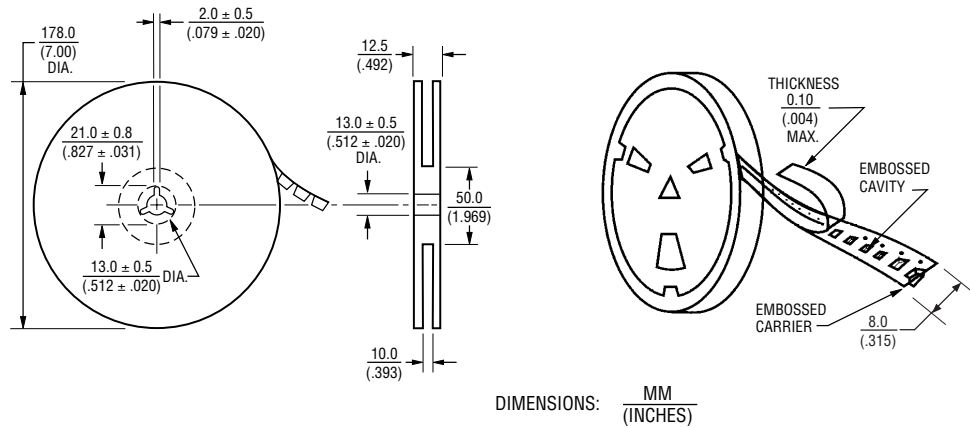
CW201212 Series - High Q Chip Inductors

BOURNS®

Soldering Profile



Packaging Specifications



REV. 01/17

Specifications are subject to change without notice.
 The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
 Users should verify actual device performance in their specific applications.